

What is claimed is:

1. An electroless plating method comprising:  
facing a surface, to be plated, of a substrate downwardly;  
5 and  
processing said surface to be plated by bringing said  
surface to be plated into contact with an electroless plating  
treatment liquid.
- 10 2. An electroless plating method according to claim 1,  
wherein gas generated on said surface to be plated is removed  
from said surface to be plated by bringing said surface to be  
plated into contact with said electroless plating treatment liquid  
in such a state that said surface to be plated is inclined.  
15
3. An electroless plating method according to claim 1,  
wherein gas generated on said surface to be plated is removed  
from said surface to be plated by forming a flow of said electroless  
plating treatment liquid in a certain direction on said surface  
20 to be plated and entraining said gas generated on said surface  
to be plated with said flow of said electroless plating treatment  
liquid.